

# Single N-channel MOSFET

## ELM4N0026FAA-N

<https://www.elm-tech.com>

### ■ General description

ELM4N0026FAA-N uses advanced trench technology to provide excellent  $R_{ds(on)}$ , low gate charge and low gate threshold voltage.

### ■ Features

- $V_{ds}=100V$
- $I_d=7.5A$  ( $V_{gs}=10V$ )
- $R_{ds(on)} = 20m\Omega$  ( $V_{gs}=10V$ )
- $R_{ds(on)} = 25m\Omega$  ( $V_{gs}=4.5V$ )

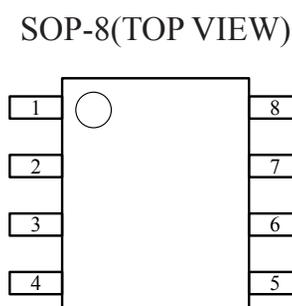
### ■ Maximum absolute ratings

Parameter	Symbol	Limit	Unit	Note	
Drain-source voltage	$V_{ds}$	100	V		
Gate-source voltage	$V_{gs}$	$\pm 20$	V		
Continuous drain current ( $V_{gs}=10V$ )	$I_d$	$T_a=25^\circ C$	7.5	A	1
		$T_a=70^\circ C$	6.0		
Pulsed drain current	$I_{dm}$	40	A	2	
Single pulse avalanche energy	EAS	16	mJ	3	
Avalanche current	$I_{as}$	18	A		
Total power dissipation	$P_d$	2.5	W	4	
					$T_a=25^\circ C$
Storage temperature range	$T_{stg}$	- 55 to 150	$^\circ C$		
Operating junction temperature range	$T_j$	- 55 to 150	$^\circ C$		

### ■ Thermal characteristics

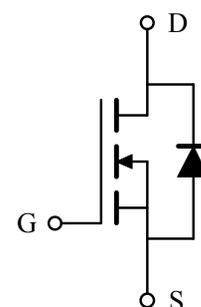
Parameter	Symbol	Typ.	Max.	Unit	Note
Thermal resistance junction-ambient	$R_{\theta ja}$	-	50	$^\circ C/W$	1
Thermal resistance junction-ambient		Steady-state	-	85	

### ■ Pin configuration



Pin No.	Pin name
1	SOURCE
2	SOURCE
3	SOURCE
4	GATE
5	DRAIN
6	DRAIN
7	DRAIN
8	DRAIN

### ■ Circuit



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## ■Electrical characteristics

T<sub>j</sub>=25°C. Unless otherwise noted.

Parameter	Symbol	Condition	Min.	Typ.	Max.	Unit	Note
<b>STATIC PARAMETERS</b>							
Drain-source breakdown voltage	BV <sub>dss</sub>	V <sub>gs</sub> =0V, I <sub>d</sub> =250μA	100	-	-	V	
BV <sub>dss</sub> temperature coefficient	$\frac{\Delta BV_{dss}}{\Delta T_j}$	Reference to 25°C, I <sub>d</sub> =1mA	-	0.08	-	V/°C	
Static drain-source on-resistance	R <sub>ds(on)</sub>	V <sub>gs</sub> =10V, I <sub>d</sub> =7A	-	16	20	mΩ	2
		V <sub>gs</sub> =4.5V, I <sub>d</sub> =5A	-	19	25		
Gate threshold voltage	V <sub>gs(th)</sub>	V <sub>gs</sub> =V <sub>ds</sub> , I <sub>d</sub> =250μA	1.2	-	2.5	V	
V <sub>gs(th)</sub> temperature coefficient	ΔV <sub>gs(th)</sub>		-	-5.5	-	mV/°C	
Drain-source leakage current	I <sub>dss</sub>	V <sub>ds</sub> =80V, V <sub>gs</sub> =0V	-	-	10	μA	
		V <sub>ds</sub> =80V, V <sub>gs</sub> =0V, T <sub>j</sub> =55°C	-	-	100		
Gate-source leakage current	I <sub>gss</sub>	V <sub>gs</sub> =±20V, V <sub>ds</sub> =0V	-	-	±100	nA	
Forward transconductance	G <sub>fs</sub>	V <sub>ds</sub> =5V, I <sub>d</sub> =7A	-	24	-	S	
Continuous source current	I <sub>s</sub>	V <sub>gs</sub> =V <sub>ds</sub> =0V, Force current	-	-	7	A	1, 5
Pulsed source current	I <sub>sm</sub>		-	-	40	A	2, 5
Diode forward voltage	V <sub>sd</sub>	V <sub>gs</sub> =0V, I <sub>s</sub> =1A	-	-	1.2	V	2
<b>DYNAMIC PARAMETERS</b>							
Input capacitance	C <sub>iss</sub>	V <sub>ds</sub> =15V, V <sub>gs</sub> =0V, f=1MHz		1930		pF	
Output capacitance	C <sub>oss</sub>				245		pF
Reverse transfer capacitance	C <sub>rss</sub>				125		pF
Gate resistance	R <sub>g</sub>	V <sub>ds</sub> =0V, V <sub>gs</sub> =0V, f=1MHz	-	1.6	-	Ω	
<b>SWITCHING PARAMETERS</b>							
Total gate charge (10V)	Q <sub>g</sub>	V <sub>ds</sub> =80V, V <sub>gs</sub> =10V I <sub>d</sub> =7A	-	36	-	nC	
Gate-source charge	Q <sub>gs</sub>		-	5	-	nC	
Gate-drain charge	Q <sub>gd</sub>		-	10	-	nC	
Turn-on delay time	t <sub>d(on)</sub>	V <sub>ds</sub> =50V, V <sub>gs</sub> =10V R <sub>gen</sub> =3.3Ω, I <sub>d</sub> =7A	-	11.5	-	ns	
Turn-on rise time	t <sub>r</sub>		-	29.0	-	ns	
Turn-off delay time	t <sub>d(off)</sub>		-	42.0	-	ns	
Turn-off fall time	t <sub>f</sub>		-	18.0	-	ns	
Reverse recovery time	t <sub>rr</sub>	I <sub>f</sub> =7A, di/dt=100A/μs	-	48	-	nS	
Reverse recovery charge	Q <sub>rr</sub>		-	29	-	nC	

Note :

1. The data tested by surface mounted on a 1 inch<sup>2</sup> FR-4 board with 2OZ copper.
2. The data tested by pulsed, pulse width ≤ 300us, duty cycle ≤ 2%.
3. The EAS data shows Max. rating . The test condition is V<sub>dd</sub>=25V, V<sub>gs</sub>=10V, L=0.1mH.
4. The power dissipation is limited by 150°C junction temperature.
5. The data is theoretically the same as I<sub>d</sub> and I<sub>dm</sub>, in real applications, should be limited by total power dissipation.

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## ■ Typical electrical and thermal characteristics

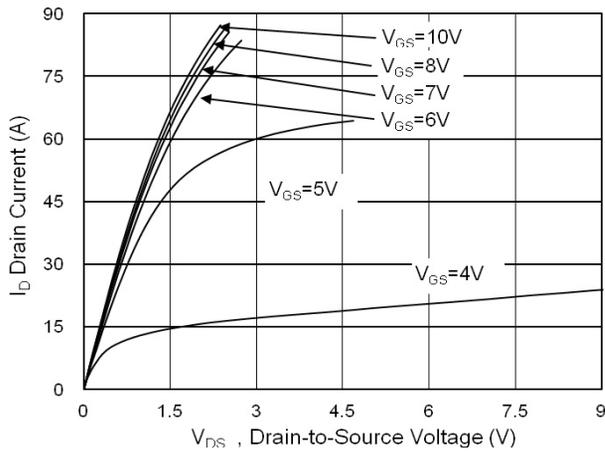


Fig.1 Typical Output Characteristics

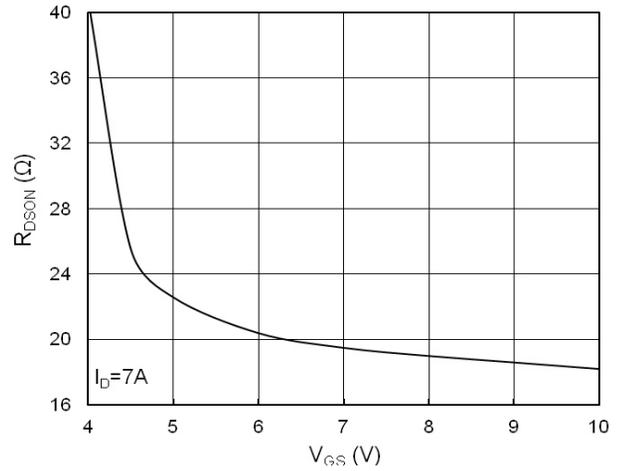


Fig.2 On-Resistance vs. Gate-Source

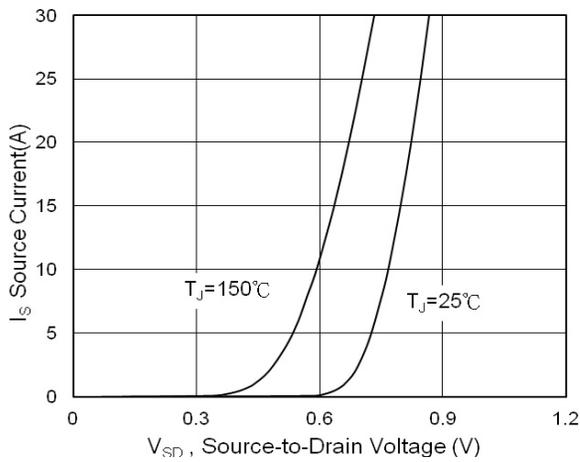


Fig.3 Forward Characteristics Of Reverse

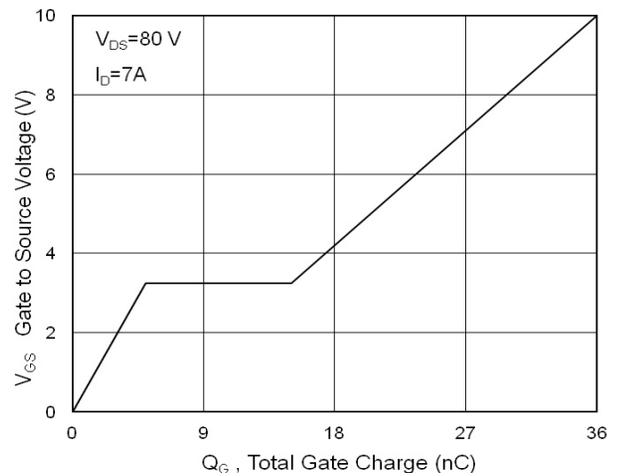


Fig.4 Gate-Charge Characteristics

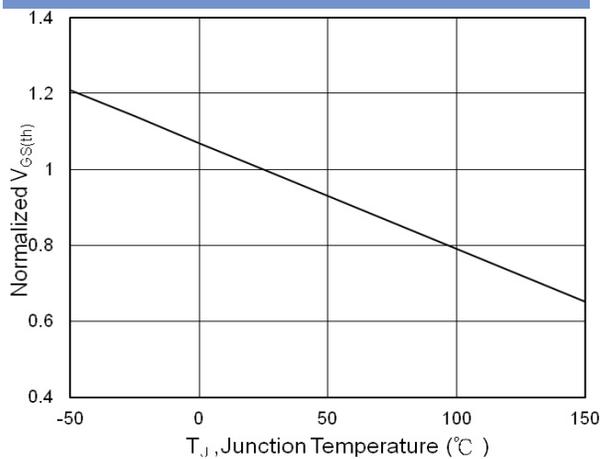


Fig.5 Normalized  $V_{GS(th)}$  vs.  $T_J$

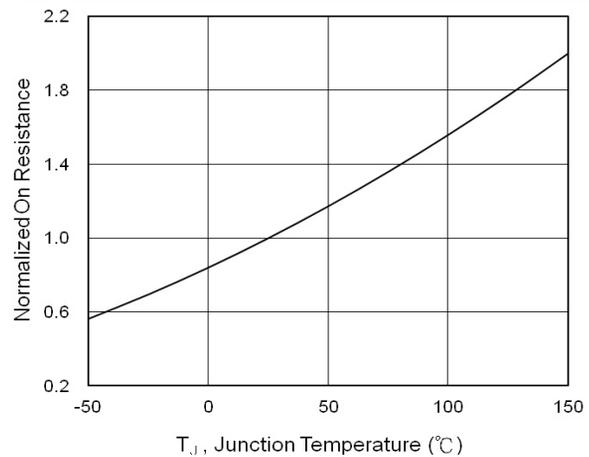


Fig.6 Normalized  $R_{DS(on)}$  vs.  $T_J$

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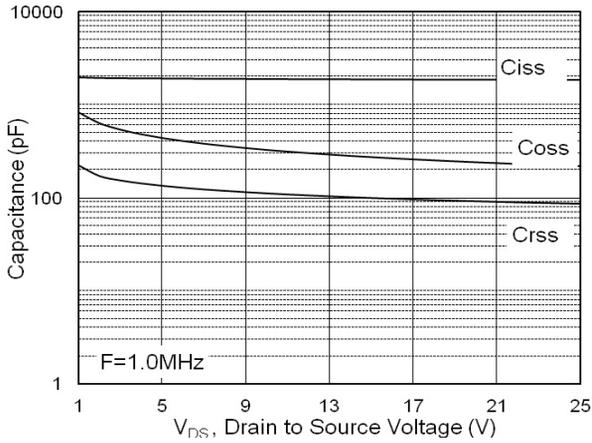


Fig.7 Capacitance

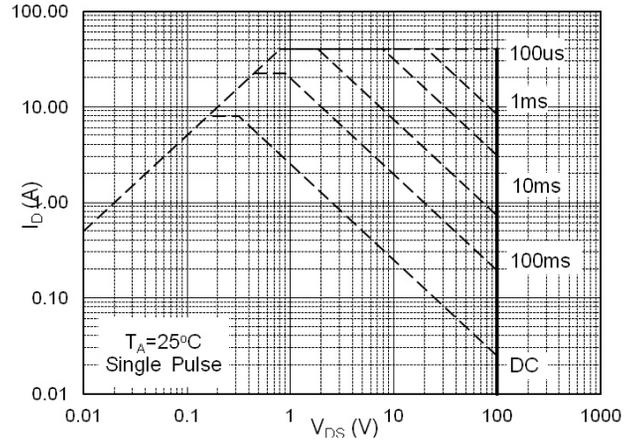


Fig.8 Safe Operating Area

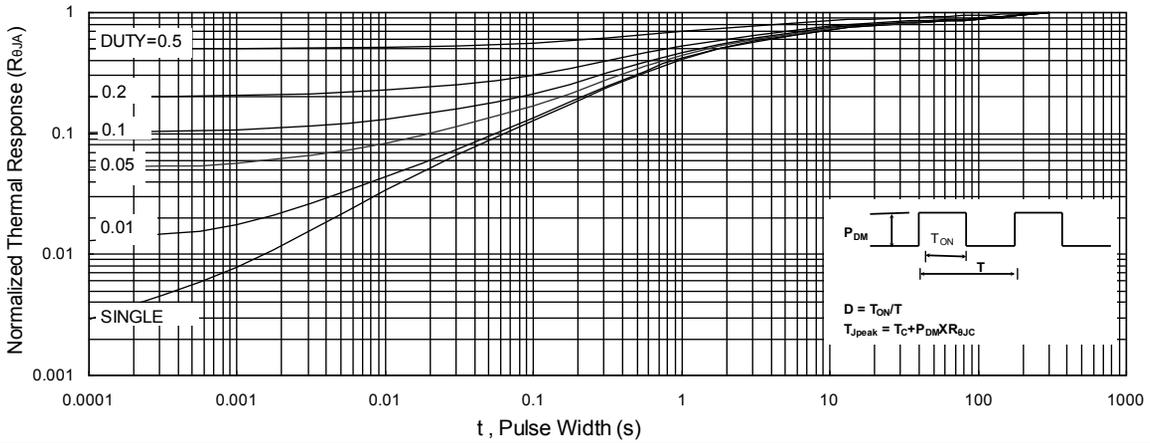


Fig.9 Normalized Maximum Transient Thermal Impedance

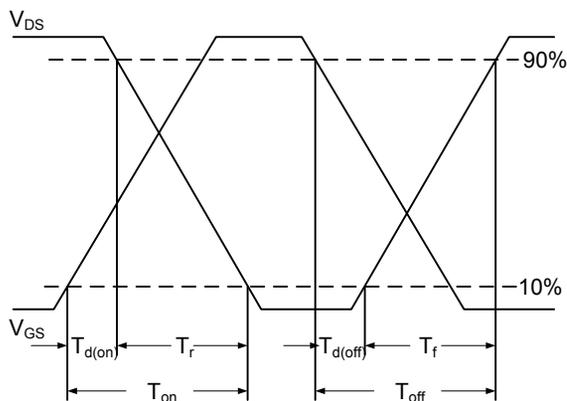


Fig.10 Switching Time Waveform

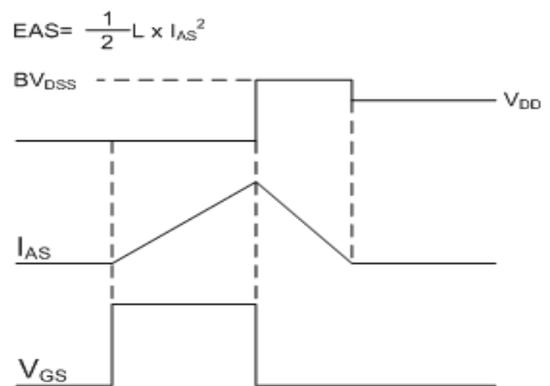


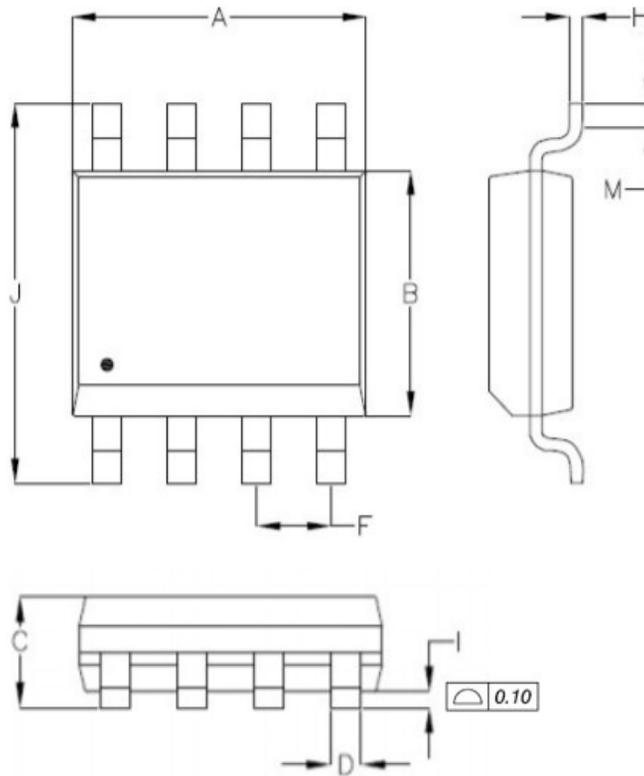
Fig.11 Unclamped Inductive Switching Waveform

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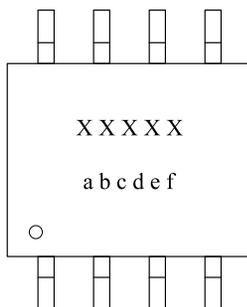
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## ■SOP-8 dimension (2,500pcs/reel)



Symbols	Millimeters		Inches	
	Min.	Max.	Min.	Max.
A	4.700	5.150	0.185	0.203
B	3.700	4.100	0.146	0.161
C	1.230	1.753	0.048	0.069
D	0.310	0.510	0.012	0.020
F	1.070	1.470	0.042	0.058
H	0.160	0.254	0.006	0.010
I	0.050	0.254	0.002	0.010
J	5.750	6.250	0.226	0.246
M	0.400	1.270	0.016	0.050

## ■Marking



Symbols	Content
xxxxxx	Product code
a	Yearly code: 2019=K, 2020=L, 2021=M, 2022=N...
b, c	Weekly code: 01 to 53
d, e	Sequence: 01 to 99 or 0A to 0Z
f	Assembly code: A to Z (I, O excepted)